

RF SWITCH

0.1 to 6.0GHz SP3T Switch

DESCRIPTION

FEATURESControl voltage :

High Isolation :

Power handling :

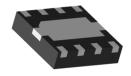
 $P_{in(1dB)}$ = +31.0 dBm TYP. @ VC(H) = 3.0 V, VC(L) = 0 V

Low Insertion Loss :

• The CG2430X1 is a pHEMT GaAs SP3T (<u>Single</u> <u>Pole</u> <u>Three</u> <u>Throw</u>) switch. This device can operate from 0.1GHz to 6.0GHz, having low insertion loss and high isolation.

PACKAGE

 8-pin Thin SON (X1) Package (1.5mm x 1.5mm x 0.37mm)



APPLICATIONS

• Wireless LAN (IEEE 802.11 a/b/g/n/ac)

Part Number Order Number Package Marking Description CG2430X1 CG2430X1-C2 8-pin plastic C01 Embossed tape 8 mm wide TSON Pin 1, 8 face the perforation (Pb-Free) side of the tape MOQ 10 kpcs/reel CG2430X1-EVAL CG2430X1-EVAL Evaluation Board with DC block capacitors, power supply bypass capacitors, and RF and DC connectors • MOQ 1

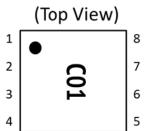
ORDERING INFORMATION

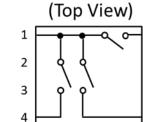
VC(H) = 1.8 to 5.0 V (3.0V TYP.) VC(L) = -0.2 to 0.2 V (0V TYP.)

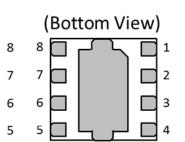
 $L_{ins} = 0.50 \text{ dB TYP}$. @ f = 2.0 to 2.5 GHz $L_{ins} = 0.60 \text{ dB TYP}$. @ f = 4.9 to 6.0 GHz

ISL = 28 dB TYP. @ f = 2.0 to 2.5 GHz ISL = 25 dB TYP. @ f = 4.9 to 6.0 GHz

PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM







Pin No.	Pin Name
1	RFC
2	GND
3	VC1
4	RF1
5	RF2
6	VC2
7	VC3
8	RF3

Remark Exposed pad : GND

TRUTH TABLE

VC1	VC2	VC3	RFC-RF1	RFC-RF2	RFC-RF3
High	Low	Low	ON	OFF	OFF
Low	High	Low	OFF	ON	OFF
Low	Low	High	OFF	OFF	ON

ABSOLUTE MAXIMUM RATINGS

$(TA = +25^{\circ}C, unless otherwise specified)$

Parameter	Symbol	Rating	Unit
Control Voltage	VC	6.0 ^{Note 1}	V
Input Power	P _{in}	+32.0 ^{Note 2}	dBm
Operating Ambient Temperature	T _A	-45 ~ +85	°C
Storage Temperature	T _{stg}	-55 ~ +150	°C

Note 1. |VC1 - VC2|≦6.0V

2. 3.0V≦|VC1 - VC2|≦5.0V

RECOMMENDED OPERATING RANGE

 $(TA = +25^{\circ}C, unless otherwise specified)$

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f	0.1	-	6.0	GHz
Switch Control Voltage (H)	VC(H)	+1.8	+3.0	+5.0	V
Switch Control Voltage (L)	VC(L)	-0.2	0	+0.2	V

ELECTRICAL CHARACTERISTICS 1

(TA=+25°C, VC(H)=3.0V, VC(L)=0V, Zo=50Ω, DC Block Capacitance=8pF, unless otherwise specified)

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Parameter	Symbol	Path	Condition	MIN.	TYP.	MAX.	Unit
Insertion Loss	L _{INS}	RFC to	f=0.1GHz to 1.0GHz Note 1	-	0.40	0.55	dB
		RF1, 2,	f=1.0GHz to 2.0GHz Note 1	-	0.40	0.55	dB
		3	f=2.0GHz to 2.5GHz	-	0.50	0.65	dB
		(ON)	f=2.5GHz to 4.9GHz	-	0.55	0.70	dB
			f=4.9GHz to 6.0GHz		0.60	0.80	dB
Isolation	ISL	RFC to	f=0.1GHz to 1.0GHz ^{Note 1}	30	33		dB
		RF1, 2,	f=1.0GHz to 2.0GHz ^{Note 1}	27	30	-	dB
		3	f=2.0GHz to 2.5GHz	25	28	-	dB
		(OFF)	f=2.5GHz to 4.9GHz	23	28	-	dB
			f=4.9GHz to 6.0GHz	20	25	-	dB
Return Loss	RL	RFC to	f=0.1GHz to 1.0GHz ^{Note 1}	15	20	-	dB
		RF1, 2,	f=1.0GHz to 2.0GHz Note 1	15	20	-	dB
		3	f=2.0GHz to 2.5GHz	15	20	-	dB
		(ON)	f=2.5GHz to 4.9GHz	15	20	-	dB
			f=4.9GHz to 6.0GHz	15	20	-	dB
0.1dB Loss Compression Input	P _{in(-0.1dB)}	RFC to RF1, 2,	f=2.5GHz	+25.0	+28.0	-	dBm
Power Note 2		3	f=6.0GHz	+25.0	+28.0	-	dBm
1dB Loss Compression Input Power	Pin(-1dB)	RFC to RF1, 2,	f=2.5GHz	+28.0	+31.0	-	dBm
Note 3		3	f=6.0GHz	+28.0	+31.0	-	dBm
3rd Order Input Intercept Point	IIP ₃		f=2.5GHz, 2-tone 5MHz Spacing	-	+55	-	dBm
2nd Harmonics	2f0		f=2.5GHz, P _{in} =+22dBm	-	75	-	dBc
3rd Harmonics	3f0		f=2.5GHz, P _{in} =+22dBm	-	70	-	dBc
Error Vector Magnitude	EVM		802.11a, 64QAM, 54Mbps, Pin≦+24dBm	-	2.5	-	%
			802.11g, 64QAM, 54Mbps, Pin≦+25dBm	-	2.5	-	%
Switching Speed	t _{SW}		f=1.0GHz	-	80	-	ns
Switch Control Current	I _{CONT}		RF none	-	2	10	uA

Note 1. DC block capacitance = 330pF at f=0.1 to 2.0GHz

2. P_{in(0.1dB)} is the measured input power level when the insertion loss increases 0.1dB more than that of the linear range.

3. P_{in(1dB)} is the measured input power level when the insertion loss increases 1dB more than that of the linear range.

ELECTRICAL CHARACTERISTICS 2

(TA=+25°C, VC(H)=1.8V, VC(L)=0V, Zo=50Ω, DC Block Capacitance=8pF, unless otherwise specified)

Parameter	Symbol	Path	Condition	MIN.	TYP.	MAX.	Unit
Insertion Loss	L _{INS}	RFC to RF1, 2,	f=0.1GHz to 1.0GHz ^{Note 1} f=1.0GHz to 2.0GHz ^{Note 1}		0.40 0.40	0.55 0.55	dB dB
		3	f=2.0GHz to 2.5GHz		0.50	0.65	dB
		(ON)	f=2.5GHz to 4.9GHz		0.55	0.70	dB
			f=4.9GHz to 6.0GHz		0.60	0.80	dB
Isolation	ISL	RFC to	f=0.1GHz to 1.0GHz Note 1	30	33		dB
		RF1, 2,	f=1.0GHz to 2.0GHz Note 1	27	30		dB
		3	f=2.0GHz to 2.5GHz	25	28		dB
		(OFF)	f=2.5GHz to 4.9GHz	23	28		dB
			f=4.9GHz to 6.0GHz	20	25		dB
Return Loss	RL	RFC to	f=0.1GHz to 1.0GHz Note 1	15	20		dB
		RF1, 2,	f=1.0GHz to 2.0GHz Note 1	15	20		dB
		3	f=2.0GHz to 2.5GHz	15	20		dB
		(ON)	f=2.5GHz to 4.9GHz	15	20		dB
			f=4.9GHz to 6.0GHz	15	20		dB
0.1dB Loss Compression Input	P _{in(-0.1dB)}	RFC to RF1, 2,	f=2.5GHz	+19.0	+22.0		dBm
Power Note 2		3	f=6.0GHz	+18.0	+21.0		dBm
1dB Loss Compression Input Power	Pin(-1dB)	RFC to RF1, 2,	f=2.5GHz	+22.0	+25.0		dBm
Note 3		3	f=6.0GHz	+21.0	+24.0		dBm
3rd Order Input Intercept Point	IIP ₃		f=2.5GHz, 2-tone 5MHz Spacing		+47		dBm
2nd Harmonics	2f0		f=2.5GHz, P _{in} =+22dBm		75		dBc
3rd Harmonics	3f0		f=2.5GHz, P _{in} =+22dBm		60		dBc
Switching Speed	t _{SW}		f=1.0GHz		150		ns
Switch Control Current	I _{CONT}		RF none		2	10	uA

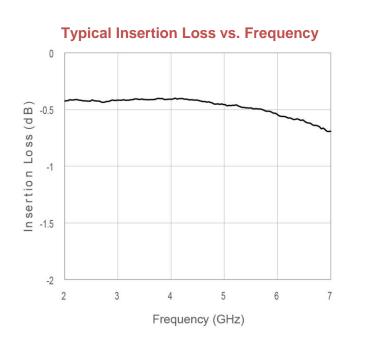
Note 1. DC block capacitance = 330pF at f=0.1 to 2.0GHz

2. P_{in(0.1dB)} is the measured input power level when the insertion loss increases 0.1dB more than that of the linear range.

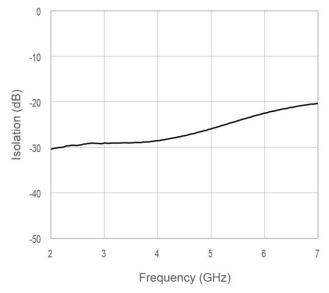
3. P_{in(1dB)} is the measured input power level when the insertion loss increases 1dB more than that of the linear range.

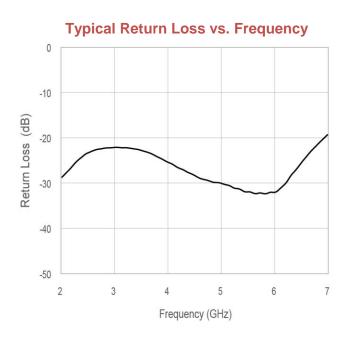
TYPICAL CHARACTERISTICS

 $(VC(H)=3V, VC(L)=0V, T_A = +25^{\circ}C, DC Block Capacitance=8pF, through board loss is subtracted in insertion loss data)$

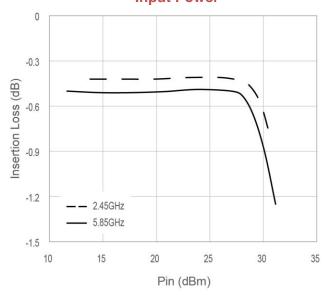


Typical Isolation vs. Frequency



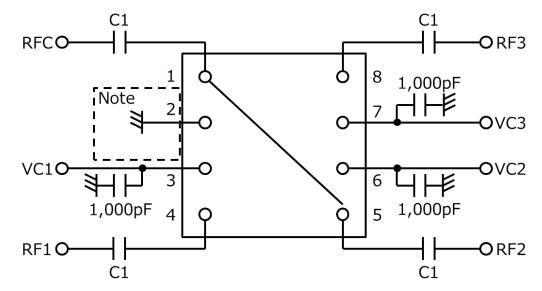


Typical Insertion Loss vs. Input Power





EVALUATION CIRCUIT



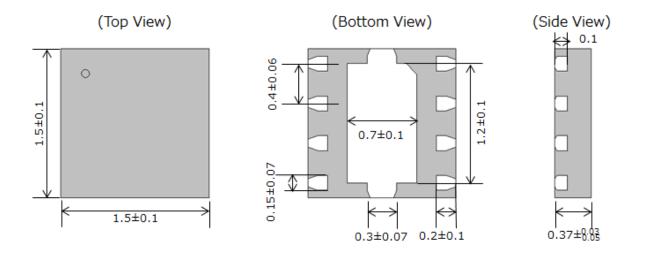
Note: It is recommended to connect the pin directly to ground, or leave unconnected.

Remarks C1 : 0.1 to 2.0 GHz 330pF : 2.0 to 6.0 GHz 8pF

The application circuits and their parameters are for reference only and are not intended for use in actual designs. DC Blocking Capacitors are required at all RF ports.

PACKAGE DIMENSIONS

8-pin Plastic TSON (Unit: mm)





RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are available on CEL's <u>Part Summary page</u> under Associated Documents



REVISION HISTORY

Version	Change to current version	Page(s)
CDS-0010-03 (Issue A)	Initial datasheet	N/A
February 17, 2016		
CDS-0010-03 (Issue B)	Added Eval Board ordering information.	1,2
March 23, 2016	Updated Marking information.	
CDS-0010-04 (Issue C)	Revised package dimensions	5
April 20, 2016	(Added tolerance spec and Pin thickness)	
CDS-0010-04 (Issue D)	Removed "Preliminary"	All
August 11, 2016		
CDS-0010-04 (Issue E)	Added "Recommended Soldering Conditions" section	6
January 11, 2017	Ŭ	
CDS-0010-06 (Issue F)	Updated Applications section	1, 3, 5
September 13, 2017	Added Error Vector Magnitude to Electrical Characteristics table 1	
	Added "Typical Characteristics" graphs section	



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